High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

ATS PART # ATS-54300R-C2-R0

Features & Benefits

- High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- Designed specifically for BGAs and other surface mount packages
- Comes preassembled with high performance thermal interface material

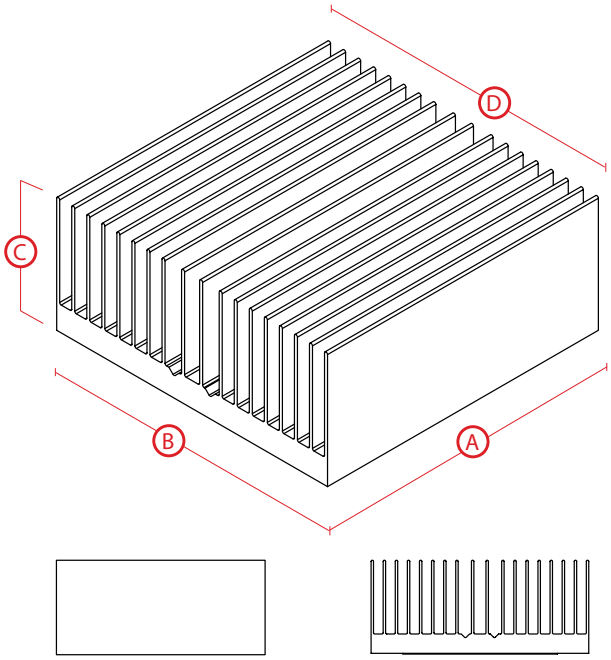


*Image above is for illustration purposes only.

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE	
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)
200	1.0	4.8	3.1
300	1.5	3.9	
400	2.0	3.3	
500	2.5	3	
600	3.0	2.7	
700	3.5	2.6	
800	4.0	2.4	

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
30 mm	30 mm	19.5 mm	30 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
2) Thermal performance data are provided for reference only. Actual performance may vary by application.
3) ATS reserves the right to update or change its products without notice to improve the design or performance.
4) Contact ATS to learn about custom options available.

ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).